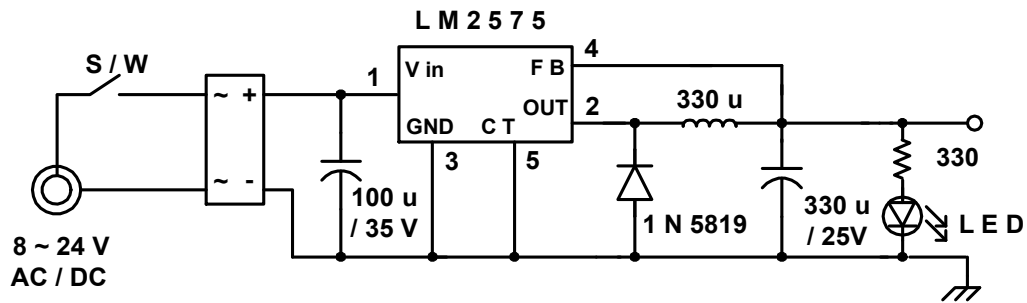
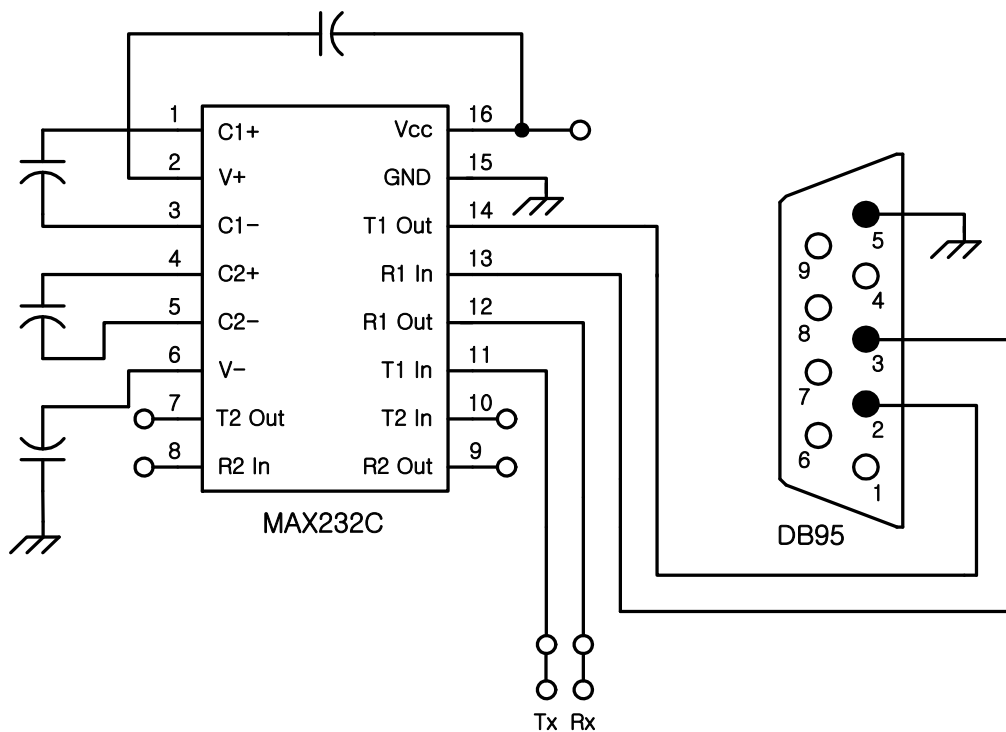


부록 3. 실험 데모 보드의 회로도

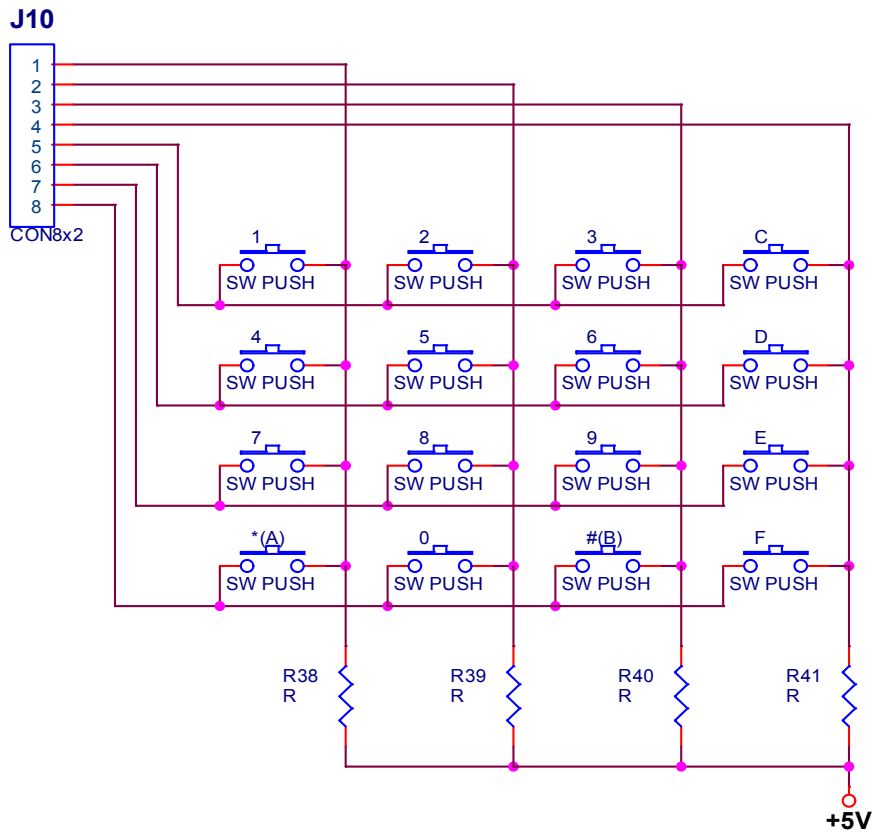
1. POWER



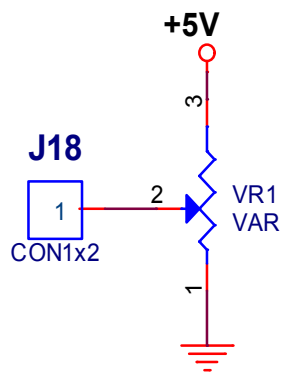
2. RS232C



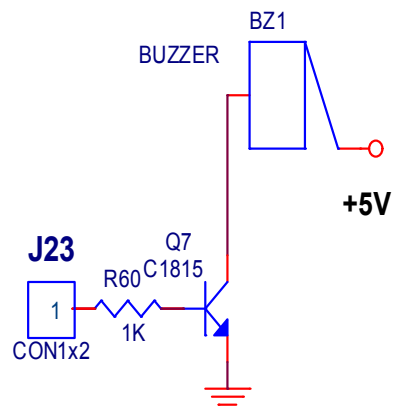
3. 4×4 KEYPAD



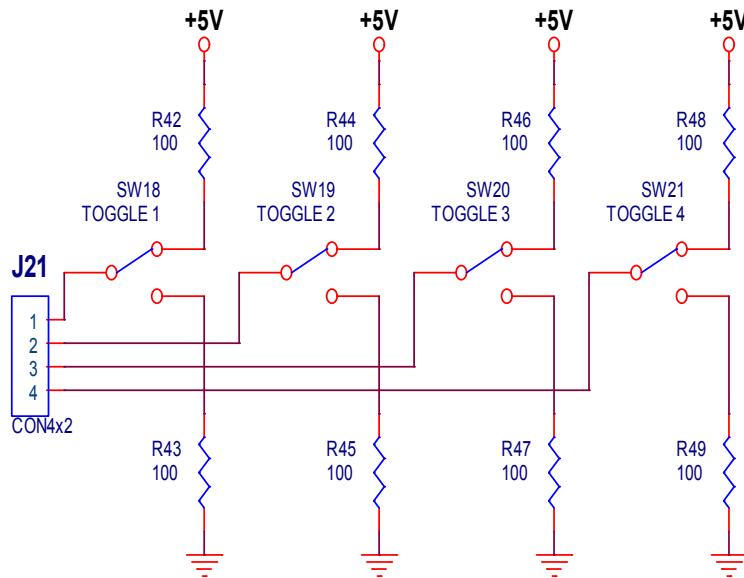
4. A/D



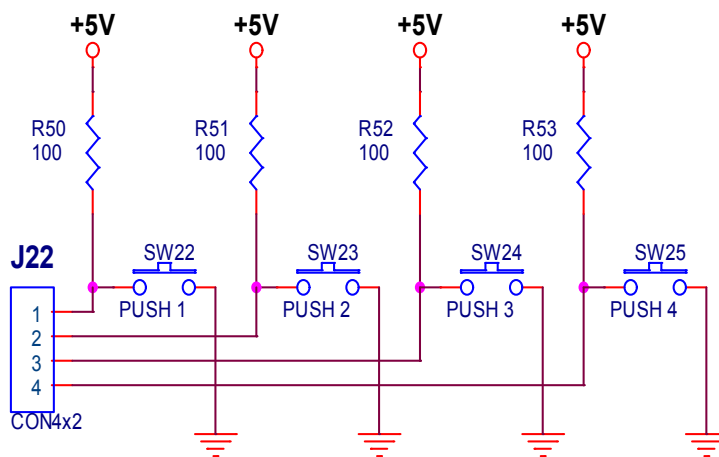
5. BUZZER



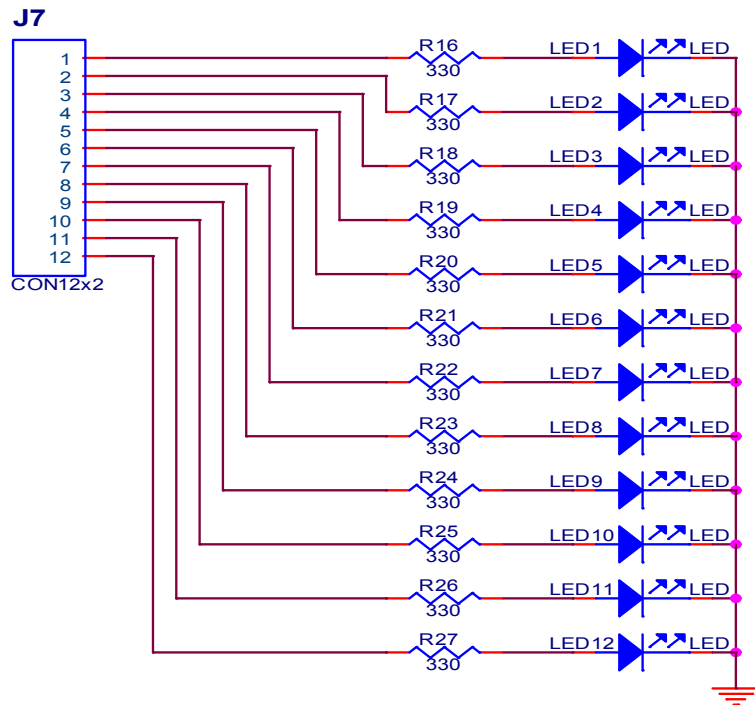
6. TOGGLE S/W



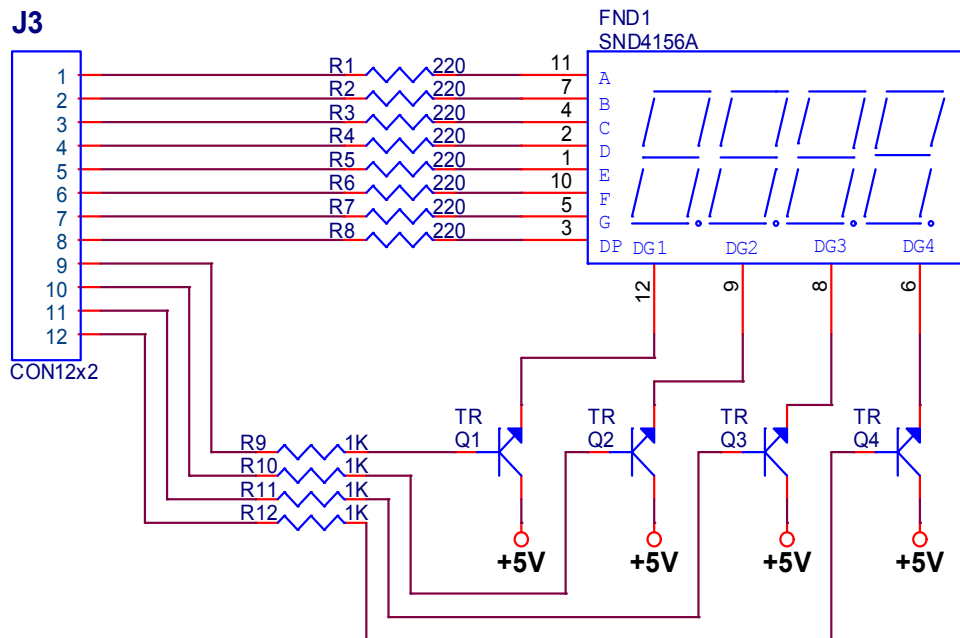
7. PUSH S/W



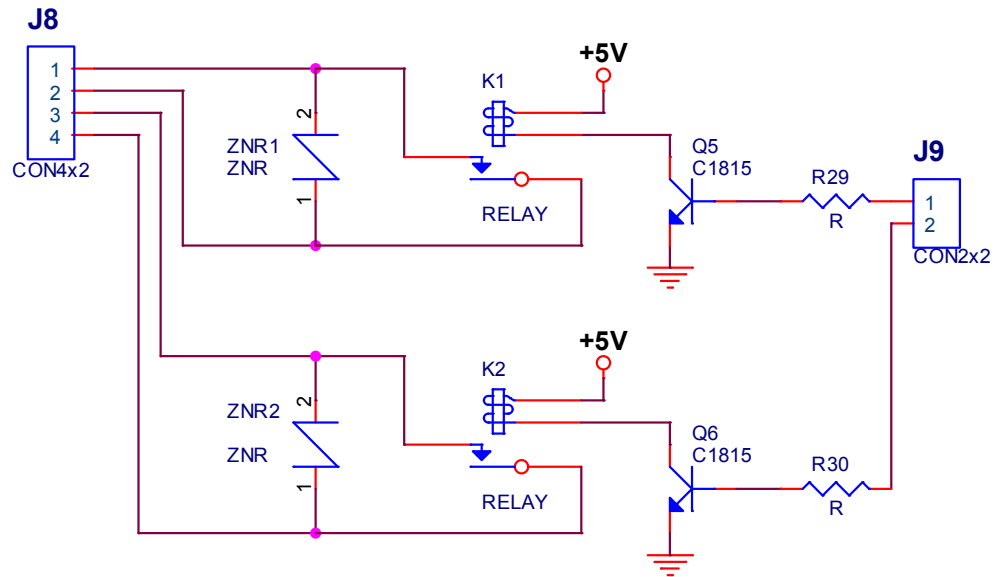
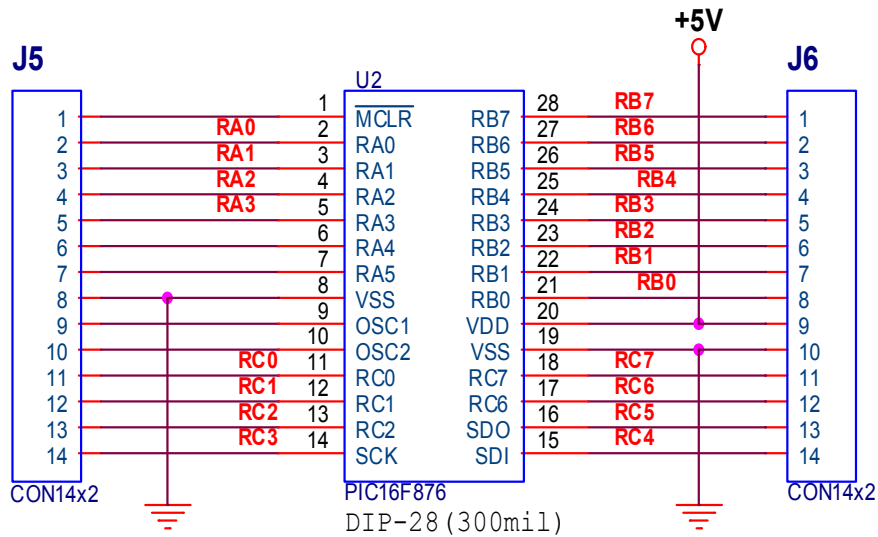
8. LED



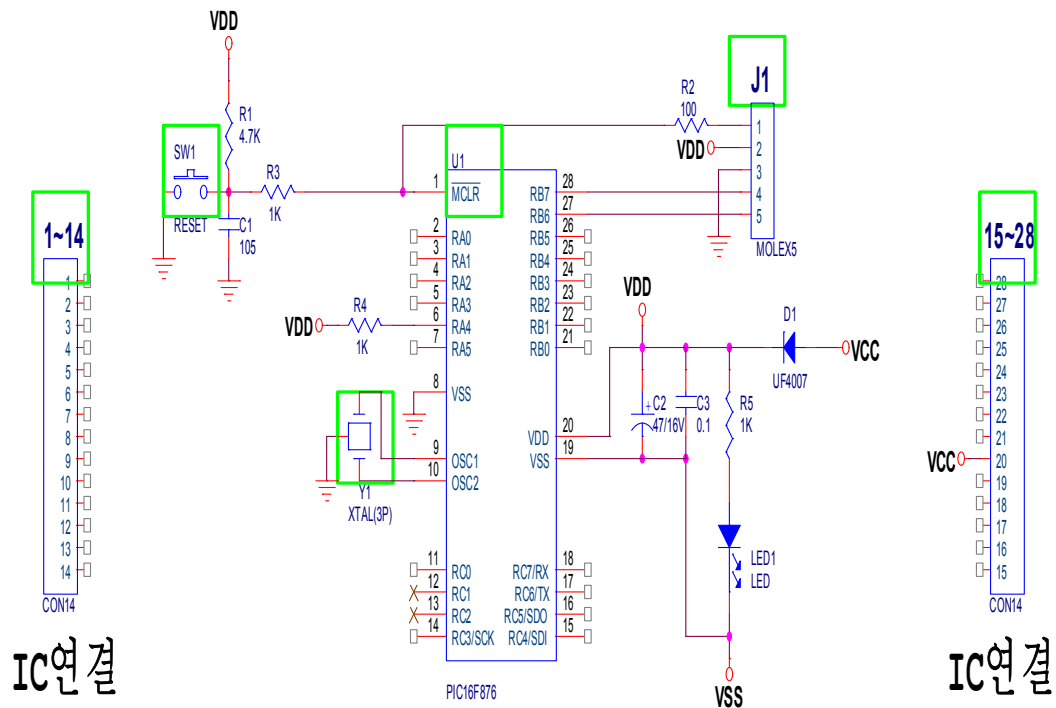
9. FND DISPLAY



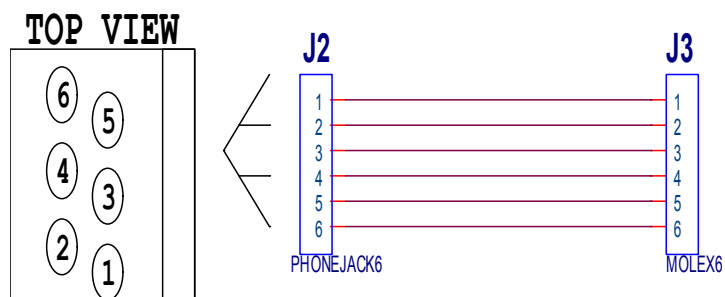
10. RELAY

11. CPU 회로
(외부연결도)

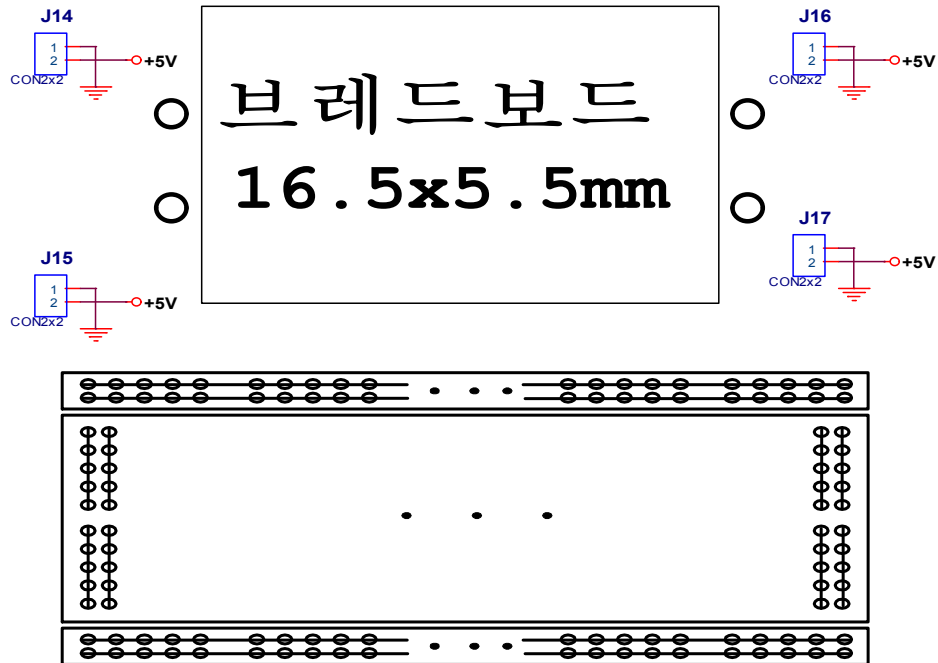
(CPU 보드 내부 회로도)



(CPU 보드와 개발장비 연결도)

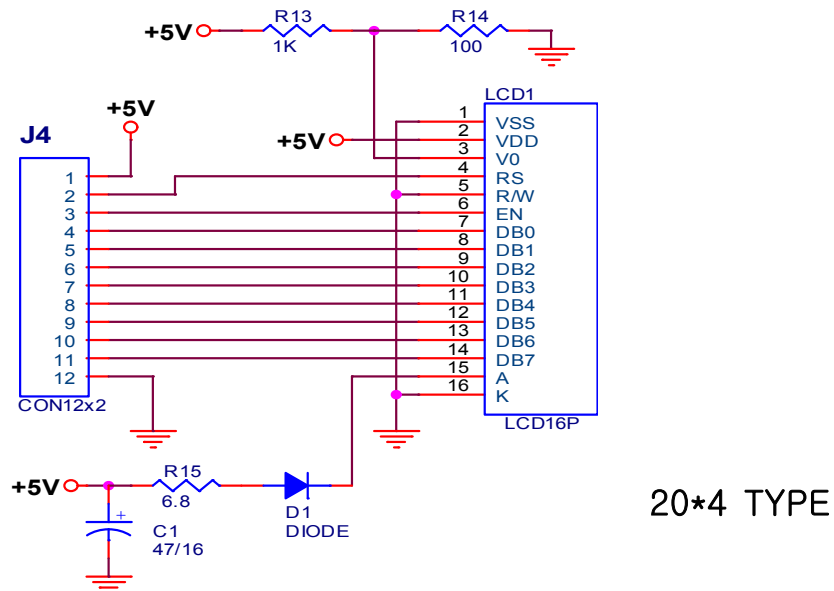


12. BREAD BOARD



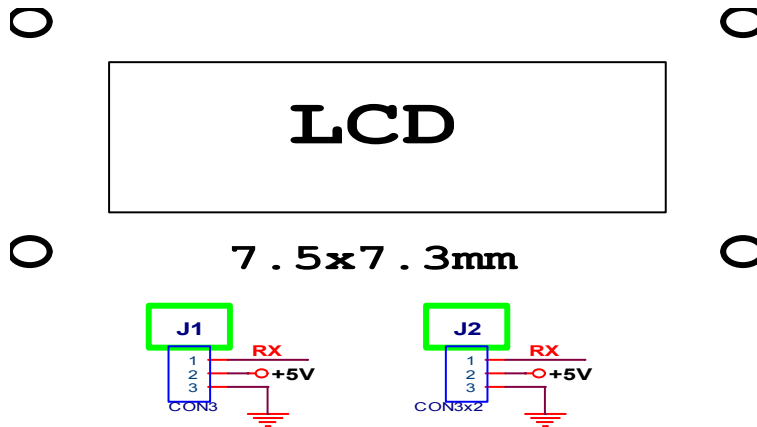
* 실선은 내부연결상태를 나타냄

13. TEXT LCD

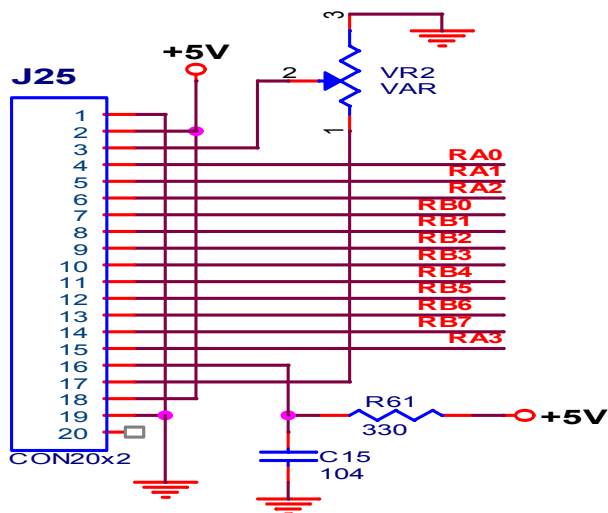


14. 시리얼 한글 LCD 모듈(HLCD114)

- 최대 11 by 4의 한글 표시 가능
- 최대 20 by 4의 영문 표시 가능
- LED 백라이트
- 한글 4층, 영문 2층
- 그래픽 LCD 도트수 128 byte
- 화면크기 $70.7 \times 30.8 \text{ mm}$
- 통신방식은 5V 레벨, 4800, N, 8, 1 사용



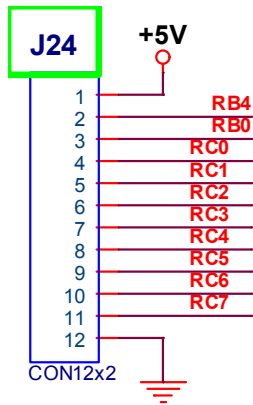
15. GRAPHIC LCD



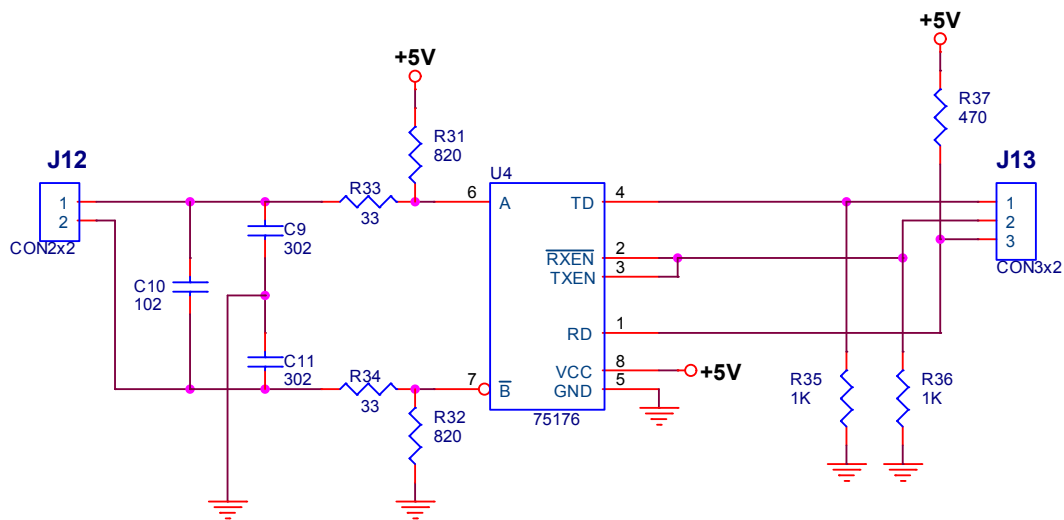
16. 외부 회로 연결용 단자대

- 용도: 별도로 주어지는 확장 보드를 이용하여 다양한 실험을 할 수 있음.

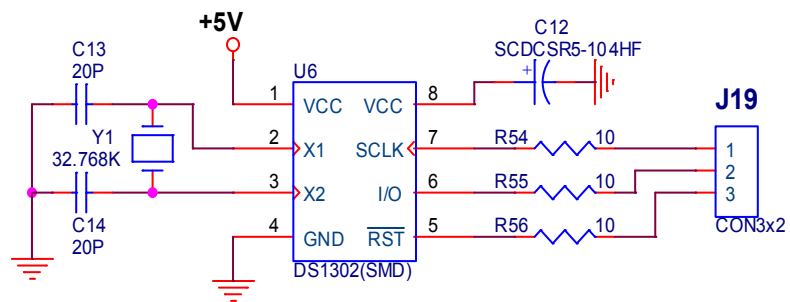
HARDWARE 구성은 CABLE로 연결하면 됨.



17. RS485 통신 INTERFACE



18. RTC(REAL TIME CLOCK) 회로



19. 온도 측정 회로

